


# MATERIAL DECLARATION SHEET



Package Type	SOT236			
Version	NiPdAu Termination			
Product Line	Semiconductor			
Compliance Date	January 1st, 2006			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight (g)	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.008972	Fused Silica (SiO <sub>2</sub> )	60676-86-0	87.70	47.58	54.25
				Epoxy Resin	129915-35-1	5.00	2.71	
				Epoxy CN	29690-82-2	2.00	1.09	
				Phenol Resin	9003-35-4	5.00	2.71	
				Carbon Black	1333-86-4	0.30	0.16	
2	Leadframe	Copper Alloy	0.006833	Copper	7440-50-8	97.66	40.35	41.31
				Iron	7439-89-6	2.30	0.95	
				Phosphorous	7723-14-0	0.03	0.01	
				Zinc	7440-66-6	0.01	0.00	
3	Chip	Silicon	0.000486	Silicon	7440-21-3	88.20	2.59	2.94
				Aluminium	7429-90-5	5.75	0.17	
				Nickel	7440-02-0	5.80	0.17	
				Gold	7440-57-5	0.25	0.01	
4	Die Attach	Epoxy	0.000080	Silver	7440-22-4	75.00	0.36	0.48
				Epoxy	Trade Secret	25.00	0.12	
5	Bond Wires	Gold	0.000088	Gold	7440-57-5	100.00	0.53	0.53
6	Terminal Finish	Preplating	0.000080	Nickel	7440-02-0	97.30	0.47	0.49
				Palladium	7440-05-3	0.86	0.01	
				Gold	7440-57-5	1.84	0.01	
		Total Weight	0.016539					